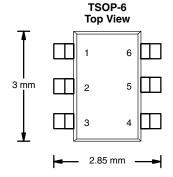


## P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
- 20	$0.0240$ at $V_{GS} = -4.5 \text{ V}$	- 8 <sup>a</sup>	21 nC			
	0.0372 at V <sub>GS</sub> = - 2.5 V	- 8 <sup>a</sup>	21110			



#### **Ordering Information:**

Si3407DV-T1-E3 (Lead (Pb)-free) Si3407DV-T1-GE3 (Lead (Pb)-free and Halogen-free)

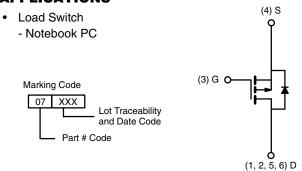
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET<sup>®</sup> Power MOSFET
- PWM Optimized
- 100 % R<sub>q</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

## Pb-free



### **APPLICATIONS**



P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATIN</b>	<b>IGS</b> (T <sub>A</sub> = 25 °C	, unless oth	erwise noted)	
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	$V_{DS}$	- 20	V	
Gate-Source Voltage	$V_{GS}$	± 12	v	
	T <sub>C</sub> = 25 °C	- I <sub>D</sub>	- 8 <sup>a</sup>	
Continuous Dusin Comment /T 150 °C)	T <sub>C</sub> = 70 °C		- 8 <sup>a</sup>	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C		- 7.5 <sup>b, c</sup>	
	T <sub>A</sub> = 70 °C	1	- 6 <sup>b, c</sup>	
Pulsed Drain Current		I <sub>DM</sub>	- 25	Α
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C		- 3.5	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	- 1.7 <sup>b, c</sup>	
Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	- 8	
Single Pulse Avalanche Energy	L = 0.1 IIII	E <sub>AS</sub>	3.2	mJ
	T <sub>C</sub> = 25 °C		4.2	
Manipular Barray Discipation	T <sub>C</sub> = 70 °C	_	2.7	w
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	2 <sup>b, c</sup>	vv
	T <sub>A</sub> = 70 °C	1	1.3 <sup>b, c</sup>	
Operating Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	45	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	25	30	7 5/**		

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s
- d. Maximum under steady state conditions is 110 °C/W.



Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static	, ,			, ,,,		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	J 050 vA		-18.7		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = - 250 μA		3.7		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = -250 \mu A$	- 0.65		- 1.5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
7 0 1 1/1 5 1 0 1		V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V			- 1	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 25			Α
		$V_{GS} = -4.5 \text{ V}, I_D = -7.5 \text{ A}$		0.0200	0.0240	Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -6.4 \text{ A}$		0.0310	0.0327	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 7.5 A		25		S
Dynamic <sup>b</sup>				•		
Input Capacitance	C <sub>iss</sub>			1670		
Output Capacitance	C <sub>oss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		335		pF
Reverse Transfer Capacitance	C <sub>rss</sub>			284		
Tatal Cata Chausa	Qg	$V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -7.5 \text{ A}$		42	63	nC
Total Gate Charge				21	32	
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -7.5 \text{ A}$		6		
Gate-Drain Charge	$Q_{gd}$			5		
Gate Resistance	$R_g$	f = 1 MHz	1.3	6.5	13	Ω
Turn-on Delay Time	t <sub>d(on)</sub>			8	16	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 10 V, $R_L$ = 1.7 $\Omega$		11	17	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ - 6 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		65	98	
Fall Time	t <sub>f</sub>			39	59	
Turn-on Delay Time	t <sub>d(on)</sub>			32	48	
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 10 V, $R_L$ = 1.7 $\Omega$		62	93	
Turn-Off Delay Time	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ - 6 A, $\text{V}_\text{GEN}$ = - 4.5 V, $\text{R}_\text{g}$ = 1 $\Omega$		53	80	
Fall Time	t <sub>f</sub>			38	57	
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	I <sub>S</sub>	$T_C = 25  ^{\circ}C$			- 3.5	_
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				- 25	Α
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = - 6 A		- 0.8	- 1.2	٧
Body Diode Reverse Recovery Time	t <sub>rr</sub>			37	56	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			22	33	nC
verse Recovery Fall Time t <sub>a</sub>		$I_F = 6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		12		ns
Reverse Recovery Rise Time	t <sub>b</sub>	7		25		

#### Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

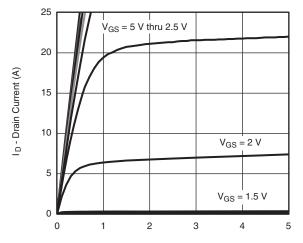
a. Pulse test; pulse width  $\leq$  300  $\mu s,$  duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.



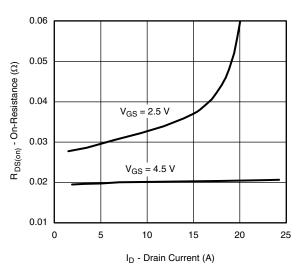


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

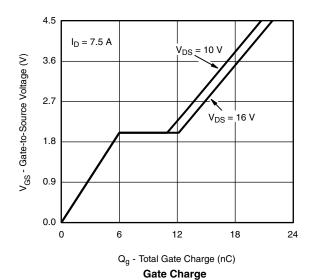


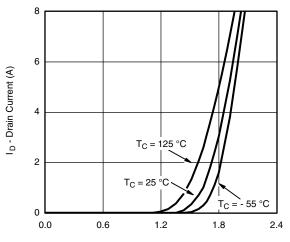
V<sub>DS</sub> - Drain-to-Source Voltage (V)

### **Output Characteristics**



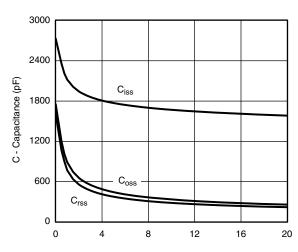
On-Resistance vs. Drain Current and Gate Voltage





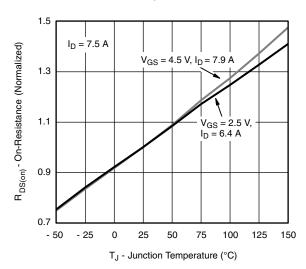
V<sub>GS</sub> - Gate-to-Source Voltage (V)

#### **Transfer Characteristics**



V<sub>DS</sub> - Drain-to-Source Voltage (V)

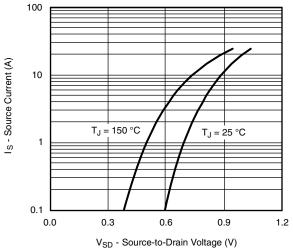
#### Capacitance



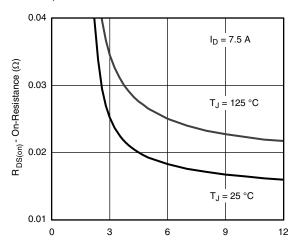
On-Resistance vs. Junction Temperature

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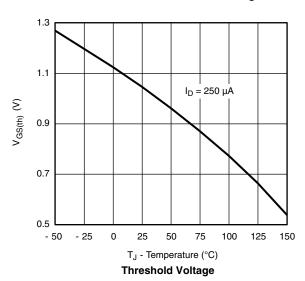
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

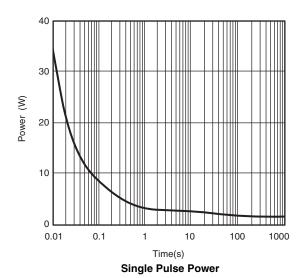


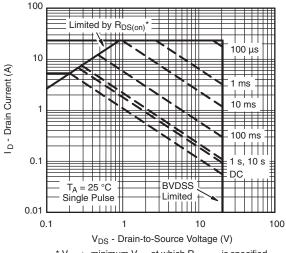
Source-Drain Diode Forward Voltage



 $V_{GS}$  - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage







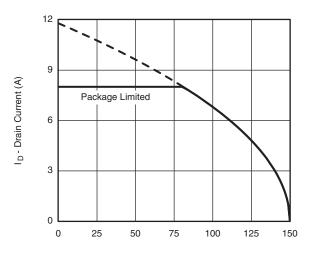
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient



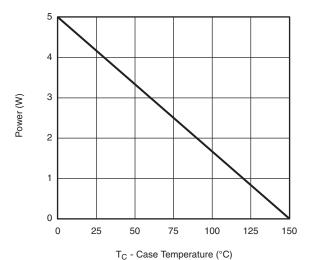


## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

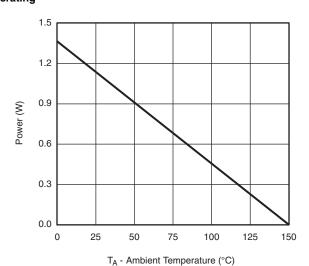


T<sub>C</sub> - Case Temperature (°C)

Current Derating\*



Power Derating, Junction-to-Foot



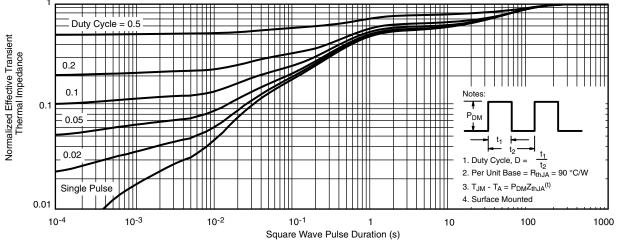
Power Derating, Junction-to-Ambient

Document Number: 69987 S09-2110-Rev. B, 12-Oct-09

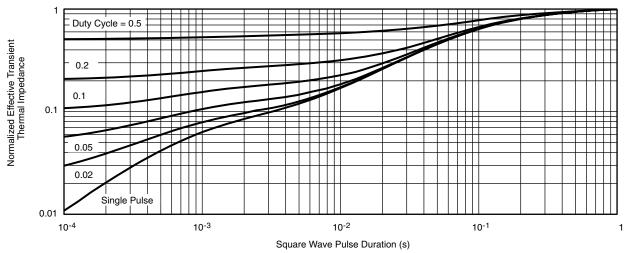
<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

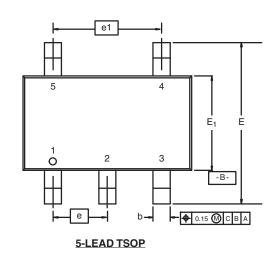
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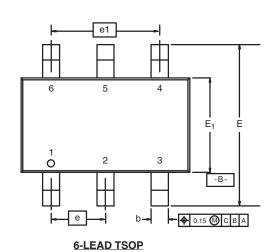


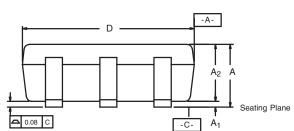


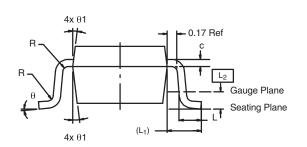
TSOP: 5/6-LEAD

**JEDEC Part Number: MO-193C** 









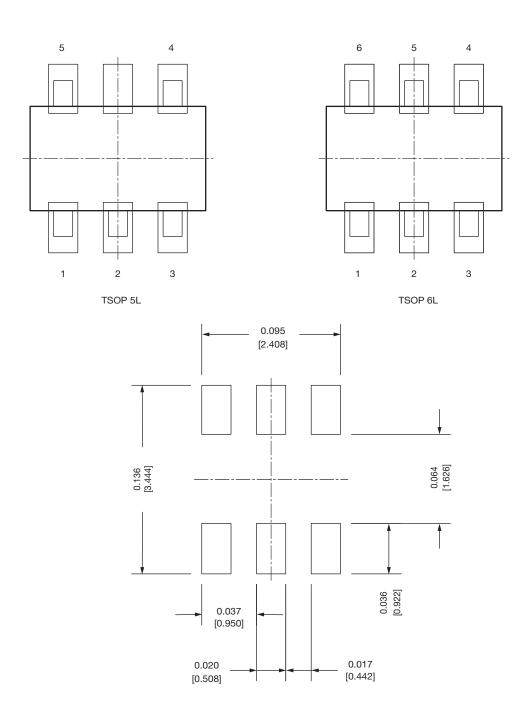
	MILLIMETERS			INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A <sub>1</sub>	0.01	-	0.10	0.0004	-	0.004	
A <sub>2</sub>	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004	0.006	0.008	
D	2.95	3.05	3.10	0.116	0.120	0.122	
E	2.70	2.85	2.98	0.106	0.112	0.117	
E <sub>1</sub>	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e <sub>1</sub>	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L <sub>1</sub>	0.60 Ref			0.024 Ref			
L <sub>2</sub>	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
$\theta_1$	7° Nom			7° Nom			
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

Document Number: 71200

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## Recommended Land Pattern For TSOP-5L / TSOP-6L



## Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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